

## AMENDMENTS TO THE CLAIMS

1. (Currently Amended) A method, comprising:  
  
applying a thermoplastic bonder to the ~~perimeter~~ perimeters of a ball grid array  
  
(BGA) package, wherein the thermoplastic bonder is applied to the BGA  
package directly between a first surface and a second surface of the BGA  
package such that the thermoplastic bonder remains at the perimeters of  
the BGA package between the first surface and the second surface;  
  
applying the thermoplastic bonder to an array of solder balls of the BGA package,  
included in the BGA package wherein the thermoplastic bonder is applied  
to the solder balls between the first surface of the BGA package and the  
solder balls, and between the second surface of the BGA package and the  
solder balls, independent of the applying of the thermoplastic bonder to  
the perimeter of the BGA package; and  
  
attaching a printable circuit board (PCB) to the BGA package ~~via the~~  
  
~~thermoplastic bonder on the perimeter of the BGA package and the array~~  
  
~~of solder balls with the thermoplastic bonder.~~
2. (Currently Amended) The method of claim 1, wherein the BGA package  
  
comprises: an integrated circuit (IC) device;  
  
~~a first surface coupled with the IC device; and~~  
  
~~solder joints to attach the array of solder balls with the first surface and a second~~  
  
~~surface.~~
3. (Currently Amended) The method of claim 1, wherein the ~~applying of the~~  
  
~~thermoplastic bonder comprises applying the bonder between the first surface~~

comprise a top surface, and the second surface comprises a bottom surface to  
provide resistance to the BGA package against warpage.

4. (Currently Amended) The method of claim ~~3~~ 1, ~~wherein the~~ further comprising  
preventing warpage of the BGA package by applying the thermoplastic bonder in  
a weakest area of the BGA package, the weakest area including the perimeters of  
the BGA package comprises at least one; ~~wherein the BGA package includes one~~  
~~or more of an opening of the BGA package, a cracking of the BGA package, a~~  
~~curving of the BGA package, bending, and a breaking of the second surface BGA~~  
~~package.~~
5. (Currently Amended) The method of claim 1, wherein the applying of the  
thermoplastic bonder to the perimeters of the BGA package further comprises  
applying the thermoplastic bonder between the first surface and the second surface  
of the BGA package such that the thermoplastic bonder is applied exclusively to  
the perimeters of the BGA package, wherein the perimeters include ~~is further~~  
~~applied to one or more of edges and corners of the BGA package.~~
6. (Currently Amended) The method of claim ~~4~~ 4, further comprising determining  
the weakest area of the BGA package to prevent the warpage ~~wherein the applying~~  
~~of the thermoplastic bonder comprises applying the thermoplastic bonder using a~~  
~~bonder dispenser.~~
7. (Cancelled)
8. (Currently Amended) The method of claim 1, wherein the ~~applying of the~~  
~~thermoplastic bonder comprises using~~ is applied via one or more of a hot melting  
jig or and a dispenser, the hot melting jig and the dispenser comprise at least one  
of a hot melt hand applicator and an adhesive unit.

9. (Cancelled)

10. (Currently Amended) The method of claim-18, wherein the independent application of the thermoplastic bonder is further applied via performed using software to control placement distance of the thermoplastic bonder with respect to the array of perimeters of the BGA package with respect to the solder balls of the BGA package.

11-31 (Cancelled)